SWITCHMODE™ Schottky Power Rectifier

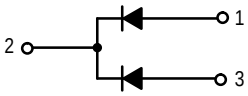
MBRF20100CT

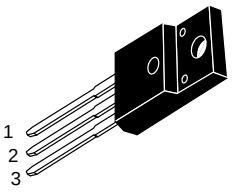
Motorola Preferred Device

SCHOTTKY BARRIER RECTIFIER 20 AMPERES 100 VOLTS

The SWITCHMODE Power Rectifier employs the Schottky Barrier principle in a large area metal–to–silicon power diode. State–of–the–art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use as rectifiers in very low–voltage, high–frequency switching power supplies, free wheeling diodes and polarity protection diodes.

- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Matched Dual Die Construction
- High Junction Temperature Capability
- High dv/dt Capability
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guardring for Stress Protection
- Epoxy Meets UL94, V_O at 1/8″
- Electrically Isolated. No Isolation Hardware Required.
- UL Recognized File #E69369(1)





CASE 221D–02
ISOLATED TO–220

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 1.9 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 units per plastic tube
- Marking: B20100

MAXIMUM RATINGS, PER LEG

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	100	Volts
Average Rectified Forward Current (Rated V_R), T_C = 133°C	Total Device	$I_{F(AV)}$	10 20	Amps
Peak Repetitive Forward Current (Rated V_R, Square Wave, 20 kHz), T_C = 133°C		I_{FRM}	20	Amps
Non–repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)		I_{FSM}	150	Amps
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)		I_{RRM}	0.5	Amp
Operating Junction and Storage Temperature		T_J, T_{stg}	– 65 to +150	°C
Voltage Rate of Change (Rated V_R)		dv/dt	10000	V/μs
RMS Isolation Voltage (t = 1.0 second, R.H. ≤ 30%, T_A = 25°C)(2)	Per Figure 3 Per Figure 4(1) Per Figure 5	V_{iso1} V_{iso2} V_{iso3}	4500 3500 1500	Volts

THERMAL CHARACTERISTICS, PER LEG

Maximum Thermal Resistance — Junction to Case	$R_{\theta JC}$	3.5	°C/W
Lead Temperature for Soldering Purposes: 1/8″ from Case for 5 Seconds	T_L	260	°C

(1) UL Recognized mounting method is per Figure 4.
(2) Proper strike and creepage distance must be provided.

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Preferred devices are Motorola recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS, PER LEG

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (3) (i_F = 10 Amp, T_C = 25°C) (i_F = 10 Amp, T_C = 125°C) (i_F = 20 Amp, T_C = 25°C) (i_F = 20 Amp, T_C = 125°C)	v_F	 0.85 0.75 0.95 0.85	Volts
Maximum Instantaneous Reverse Current (3) (Rated DC Voltage, T_C = 25°C) (Rated DC Voltage, T_C = 125°C)	i_R	 0.15 150	mA

(3) Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%

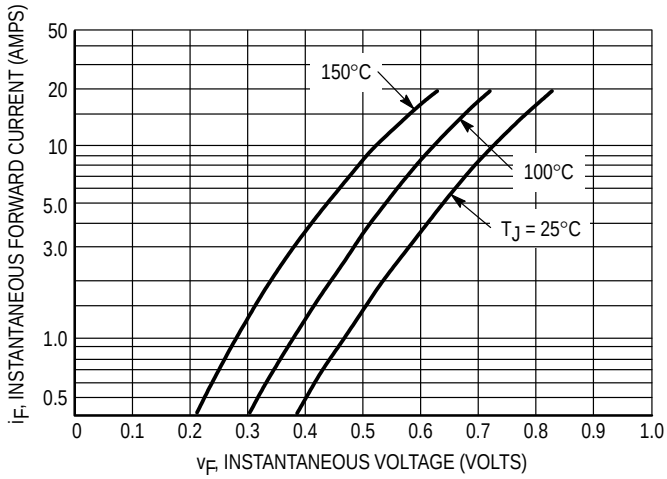


Figure 1. Typical Forward Voltage Per Diode

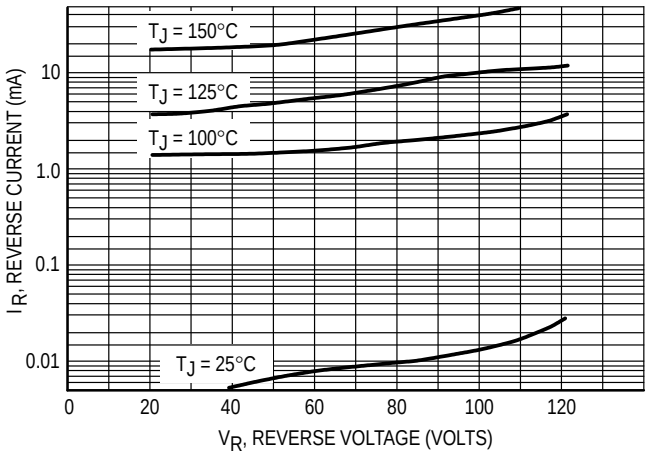


Figure 2. Typical Reverse Current Per Diode

TEST CONDITIONS FOR ISOLATION TESTS*

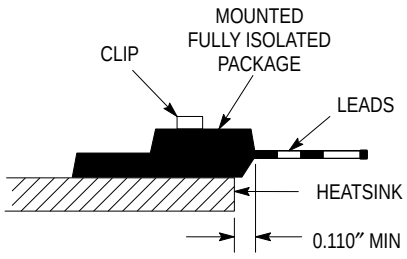


Figure 3. Clip Mounting Position for Isolation Test Number 1

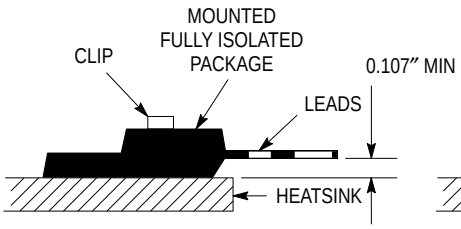


Figure 4. Clip Mounting Position for Isolation Test Number 2

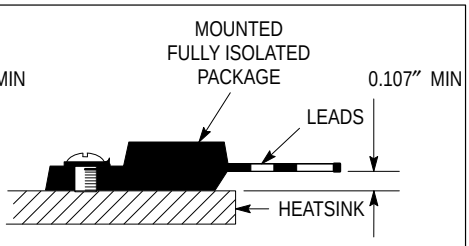
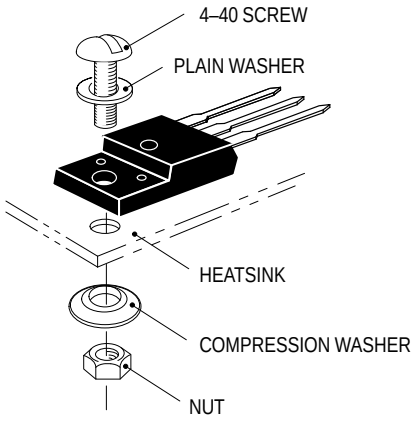


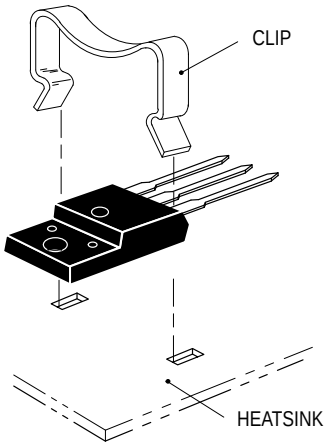
Figure 5. Screw Mounting Position for Isolation Test Number 3

* Measurement made between leads and heatsink with all leads shorted together.

MOUNTING INFORMATION**



6a. Screw–Mounted



6b. Clip–Mounted

Figure 6. Typical Mounting Techniques

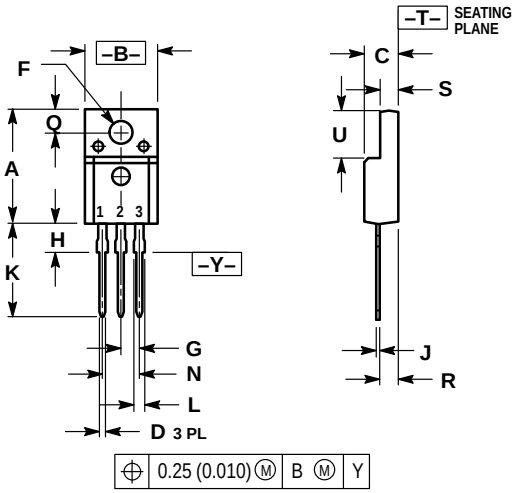
Laboratory tests on a limited number of samples indicate, when using the screw and compression washer mounting technique, a screw torque of 6 to 8 in · lbs is sufficient to provide maximum power dissipation capability. The compression washer helps to maintain a constant pressure on the package over time and during large temperature excursions.

Destructive laboratory tests show that using a hex head 4–40 screw, without washers, and applying a torque in excess of 20 in · lbs will cause the plastic to crack around the mounting hole, resulting in a loss of isolation capability.

Additional tests on slotted 4–40 screws indicate that the screw slot fails between 15 to 20 in · lbs without adversely affecting the package. However, in order to positively ensure the package integrity of the fully isolated device, Motorola does not recommend exceeding 10 in · lbs of mounting torque under any mounting conditions.

**For more information about mounting power semiconductors see Application Note AN1040.

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.621	0.629	15.78	15.97
B	0.394	0.402	10.01	10.21
C	0.181	0.189	4.60	4.80
D	0.026	0.034	0.67	0.86
F	0.121	0.129	3.08	3.27
G	0.100 BSC		2.54 BSC	
H	0.123	0.129	3.13	3.27
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
N	0.200 BSC		5.08 BSC	
Q	0.126	0.134	3.21	3.40
R	0.107	0.111	2.72	2.81
S	0.096	0.104	2.44	2.64
U	0.259	0.267	6.58	6.78

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE

CASE 221D–02
(ISOLATED TO–220)
ISSUE D

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